Amendments to th Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-6 (cancelled)

Claim 7 (currently amended): A semiconductor package, comprising:

a substrate;

a die located and supported on said substrate with an adhesive layer between them;

a plurality of signal transferring means which electrically connects said die to said substrate;

a molding compound which seals and protect said die and said plurality of signal transferring means, wherein said molding compound has geometrically a ~~concave~~ recessed portion located at the top surface of the center part, wherein said die is located right below said recessed portion and fully covered by said molding compound, so that the thickness of said molding compound above said die is less than the thickness on the other portions of said molding compound-; and

a heat-spreading device which is attached atop said molding

compound to conduct heat from said die to ambient air, wherein said heat-spreading device has a downward bump aligned to said ~~concave~~ recessed portion, and said molding compound exists between said downward bump and said die; and

a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said substrate to external circuits.

Claim 8 (original): The semiconductor package of claim 7, wherein said plurality of conductive means includes a plurality of solder balls.

Claim 9 (original): The semiconductor package of claim 7, wherein said plurality of signal transferring means can be a plurality of bonding wires.

Claim 10 (cancelled)

Claim 11 (original): The semiconductor package of claim 7, wherein said heat-spreading device can be made of metal.

Claim 12 (previously amended): The semiconductor package of claim 7, wherein said die has a thermally conductive glue, which conduct heat from

said die through said molding compound to said heat-spreading device.

Claims 13-26 (cancelled)

Claim 27 (currently amended): A semiconductor package, at least comprising:

molding means, with a ~~concave~~ recessed portion located at the central part of the top surface, for sealing and protecting a die~~,~~ which is adhered on a substrate by an adhesive layer and electrically connected to the substrate by a plurality of signal transferring means, wherein said die is located right below said recessed portion and fully covered by said molding means, so that the thickness of said molding means above said die is less than the thickness on the other portions of said molding means; and

heat-spreading means for conducting heat from said die to ambient air by attaching atop said molding means, wherein said hea~~d~~ t-spreading means has a downward bump aligned to said ~~concave~~ recessed portion, and said molding compound exists between said downward bump and said die.

Claim 28 (currently amended): The semiconductor package of claim ~~25~~ 27, further comprises a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said

substrate to external circuits.

Claim 29 (currently amended): The semiconductor package of claim ~~26~~ 28, wherein said plurality of conductive means includes a plurality of solder balls.

Claim 30 (currently amended): The semiconductor package of claim ~~25~~ 27, wherein said plurality of signal transferring means can be a plurality of bonding wires.

Claim 31 (currently amended): The semiconductor package of claim ~~25~~ 27, wherein said heat-spreading means can be made of metal.

Claim 32 (currently amended): The semiconductor package of claim ~~25~~ 27, wherein said die has a thermally conductive glue, which conduct heat from said die through said molding means to said heat-spreading device.